

# 2SK2956

# Silicon N Channel MOS FET High Speed Power Switching

REJ03G1056-0401

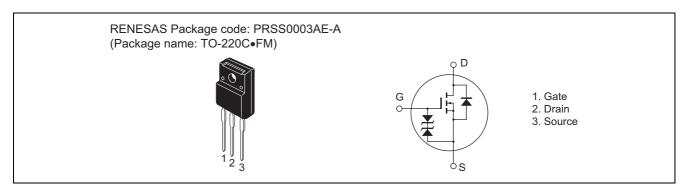
(Previous: ADE-208-566B)

Rev.4.01 Apr 27, 2006

#### **Features**

- Low on-resistance  $R_{DS(on)} = 7 \ m\Omega \ typ.$
- 4 V gate drive devices.
- High speed switching

#### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	30	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	I <sub>D</sub>	50	A
Drain peak current	I <sub>D(pulse)</sub> Note1	200	A
Body-drain diode reverse drain current	I <sub>DR</sub>	50	А
Channel dissipation	Pch Note2	35	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

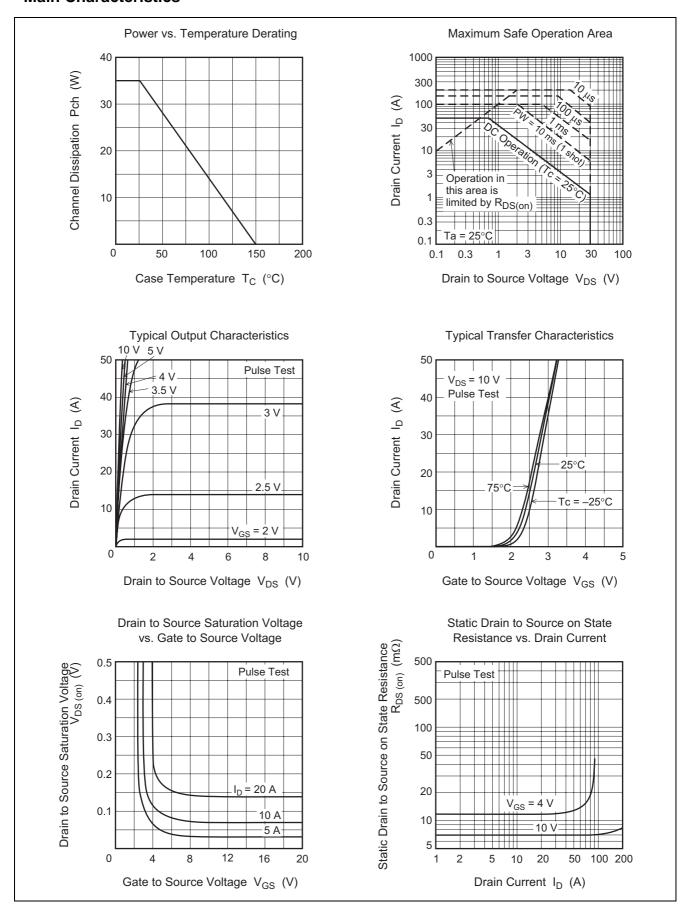
#### **Electrical Characteristics**

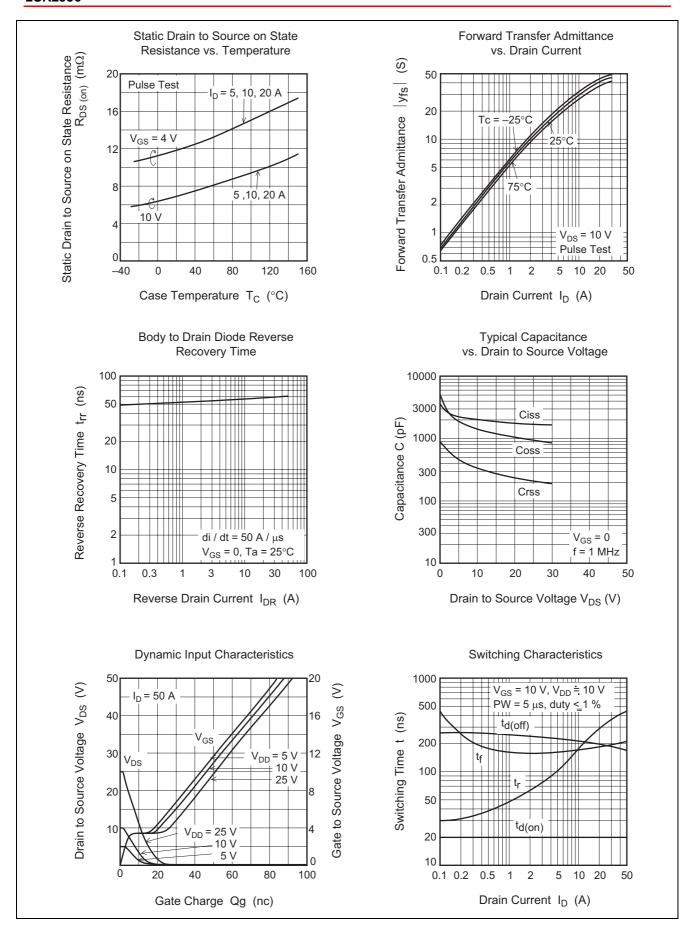
 $(Ta = 25^{\circ}C)$ 

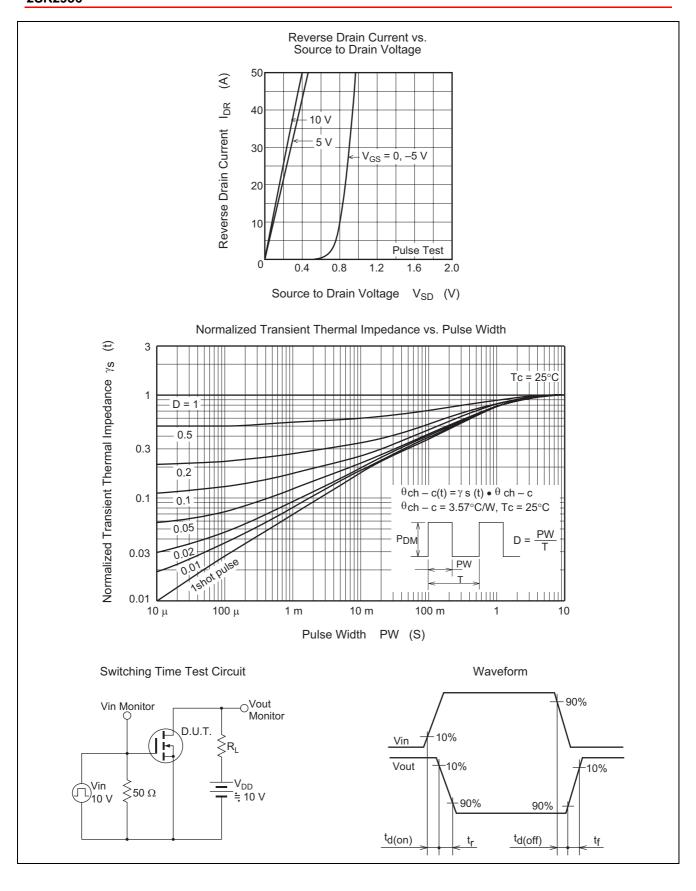
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	10	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10V$
Static drain to source on state	R <sub>DS(on)</sub>	_	7.0	10	mΩ	$I_D = 25 \text{ A}, V_{GS} = 10 \text{V}^{\text{Note3}}$
resistance	R <sub>DS(on)</sub>	_	12	18	mΩ	$I_D = 25 \text{ A}, V_{GS} = 4V^{\text{Note3}}$
Forward transfer admittance	y <sub>fs</sub>	25	45	_	S	$I_D = 25 \text{ A}, V_{DS} = 10 V^{\text{Note3}}$
Input capacitance	Ciss	_	2000	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	1500	_	pF	f = 1MHz
Reverse transfer capacitance	Crss	_	350	_	pF	
Turn-on delay time	t <sub>d(on)</sub>	_	20	_	ns	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A},$
Rise time	t <sub>r</sub>	_	330	_	ns	$R_L = 0.4 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	190	_	ns	
Fall time	t <sub>f</sub>	_	190	_	ns	
Body-drain diode forward voltage	$V_{DF}$	_	0.95	_	V	$I_F = 50 \text{ A}, V_{GS} = 0$
Body-drain diode reverse	t <sub>rr</sub>	_	60	_	ns	$I_F = 50 \text{ A}, V_{GS} = 0$
recovery time						$di_F/dt = 50 A/\mu s$

Note: 3. Pulse test

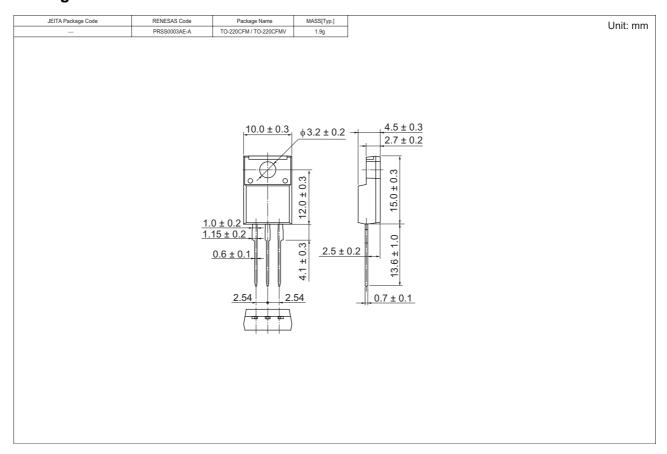
#### **Main Characteristics**







## **Package Dimensions**



### **Ordering Information**

Part Name	Quantity	Shipping Container
2SK2956-E	600 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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